TOSHIBA 2SK2989

TOSHIBA FIELD EFFECT TRANSISTOR SILICON N CHANNEL MOS TYPE (π -MOS \mathbb{V} I)

2 S K 2 9 8 9

HIGH SPEED SWITCHING APPLICATIONS

CHOPPER REGULATOR, DC-DC CONVERTER AND MOTOR DRIVE **APPLICATIONS**

Low Drain-Source ON Resistance : $R_{DS(ON)} = 120 \,\mathrm{m}\Omega$ (Typ.)

High Forward Transfer Admittance : $|Y_{fS}| = 2.6 \text{ S}$ (Typ.)

Low Leakage Current : $I_{DSS} = 100 \,\mu\text{A} \, (V_{DS} = 50 \,\text{V})$

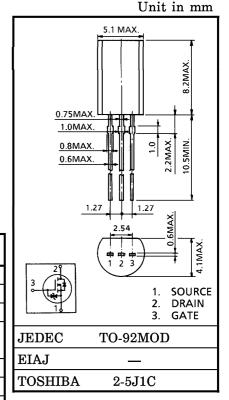
: $V_{th} = 0.8 \sim 2.0 \text{ V}$ Enhancement-Mode

 $(V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA})$

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERIS	SYMBOL RATING		UNIT		
Drain-Source Voltage	${ m v_{DSS}}$	50	V		
Drain-Gate Voltage (RG	${ m v_{DGR}}$	50	V		
Gate-Source Voltage	v_{GSS}	±20	V		
Drain Current	DC	$I_{\mathbf{D}}$	5	A	
	Pulse	I_{DP}	15		
Drain Power Dissipation	$P_{\mathbf{D}}$	0.9	W		
Channel Temperature	$\mathrm{T_{ch}}$	150	°C		
Storage Temperature Ra	$\mathrm{T_{stg}}$	-55~150	°C		

INDUSTRIAL APPLICATIONS



THERMAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Resistance, Channel to Ambient	R _{th (ch-a)}	138	°C/W

This transistor is an electrostatic sensitive device. Please handle with caution.

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ELECTRICAL CHARACTERISTICS (Ta = 25°C)

СНАВА	CTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
		STMBOL		WIIIN.	111.		ONII
Gate Leakag		IGSS	$V_{GS} = \pm 16 V, V_{DS} = 0 V$	_	_	±10	μ A
Drain Cut-of	f Current	$I_{ m DSS}$	$V_{DS} = 50 \text{ V}, \ V_{GS} = 0 \text{ V}$		_	100	μ A
Drain-Source Voltage	Breakdown	V (BR) DSS	$I_{ m D} = 10 \ { m mA}, \ { m V}_{ m GS} = 0 \ { m V}$	50	_	_	V
Gate Thresho	old Voltage	$V_{ m th}$	$V_{\mathrm{DS}} = 10 \mathrm{V}, \mathrm{I}_{\mathrm{D}} = 1 \mathrm{mA}$	0.8	_	2.0	V
Drain-Source	ON Resistance	R _{DS} (ON)	$V_{GS} = 4 \text{ V}, I_{D} = 1.3 \text{ A}$ $V_{GS} = 10 \text{ V}, I_{D} = 2.5 \text{ A}$		240 120	330 150	$\mathbf{m}\Omega$
Forward Tran Admittance	nsfer	Y _{fs}	$V_{ m DS} = 10 \ m V, \ I_{ m D} = 2.5 \ m A$	1.3	2.6		S
Input Capaci	Input Capacitance			_	145	_	
Reverse Transfer Capacitance		$egin{array}{ccc} C_{ ext{iss}} & & & & & \\ C_{ ext{rss}} & & & & & & \\ \end{array}$	$egin{aligned} { m V}_{ m DS} &= 10 { m V}, \; { m V}_{ m GS} &= 0 { m V} \ { m f} &= 1 { m MHz} \end{aligned}$	_	25	_	pF
Output Capacitance		Coss		_	75	_	
Switching Time F	Rise Time	t _r	$V_{GS} \stackrel{10 \text{ V}}{\underset{\text{O V}}{\text{ID}}} = 2.5 \text{ A}$ $V_{GS} \stackrel{\text{O V}}{\underset{\text{O V}}{\text{OUT}}} = 2.5 \text{ A}$ $R_{L} = 10 \Omega$ $V_{DD} = 25 \text{ V}$	_	16	_	
	Turn-on Time	t _{on}		_	23	_	ns
	Fall Time	tf		_	27	_	115
	Turn-off Time	t _{off}	$V_{\mathrm{IN}}: \mathrm{t_r}, \mathrm{t_f} < 5 \mathrm{ns}, \ \mathrm{Duty} \leq 1\%, \mathrm{t_W} = 10 \mu \mathrm{s}$		110	_	
Total Gate Charge (Gate- Source Plus Gate-Drain)		\mathbf{Q}_{g}	$V_{\mathrm{DD}} = 40 \mathrm{V}, V_{\mathrm{GS}} = 10 \mathrm{V}$	_	6.5	_	nC
Gate-Source Charge		$\mathbf{Q}_{\mathbf{g}\mathbf{s}}$	$I_{D} = 5 A$		5	_	
Gate-Drain ("Miller") Charge		$ m Q_{gd}$		_	1.5	<u> </u>	

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	$I_{ m DR}$	_	_	_	5	A
Pulse Drain Reverse Current	$I_{ m DRP}$		_	_	15	Α
Diode Forward Voltage	$v_{ m DSF}$	$I_{DR} = 5 A$, $V_{GS} = 0 V$	_	_	-1.5	V

MARKING

